

MOS FIELD EFFECT TRANSISTOR μ PA1724

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

* DESCRIPTION

The μ PA1724 is N-Channel MOS Field Effect Transistor designed for power management applications of notebook computers and so on.

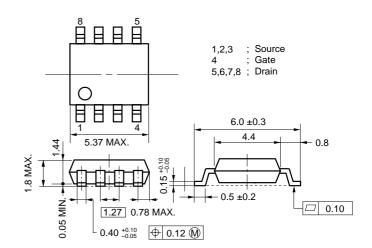
FEATURES

- 2.5-V gate drive and low on-resistance
 - RDS(on)1 = 11.0 m Ω MAX. (VGS = 4.5 V, ID = 5.0 A)
- ★ RDS(on)2 = 12.0 m Ω MAX. (VGS = 4.0 V, ID = 5.0 A)
 - $R_{DS(on)3} = 15.0 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = 2.5 \text{ V, ID} = 5.0 \text{ A)}$
 - Low Ciss: Ciss = 1850 pF TYP.
 - Built-in G-S protection diode
 - Small and surface mount package (Power SOP8)

ORDERING INFORMATION

| PART NUMBER | PACKAGE | | |
|-------------|------------|--|--|
| μPA1724G | Power SOP8 | | |

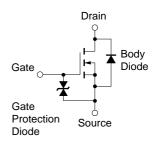
PACKAGE DRAWING (Unit: mm)



ABSOLUTE MAXIMUM RATINGS (TA = 25°C, All terminals are connected.)

| Drain to Source Voltage (Vgs = 0 V) | VDSS | 20 | V |
|---|-----------|-------------|----|
| Gate to Source Voltage (Vps = 0 V) | Vgss | ±12 | V |
| Drain Current (DC) | ID(DC) | ±10 | Α |
| Drain Current (pulse) Note1 | D(pulse) | ±40 | Α |
| Total Power Dissipation $(T_A = 25^{\circ}C)^{Note2}$ | Рт | 2.0 | W |
| Channel Temperature | Tch | 150 | °C |
| Storage Temperature | T_{stg} | -55 to +150 | °C |

EQUIVALENT CIRCUIT



- **Notes 1.** PW \leq 10 μ s, Duty Cycle \leq 1 %
 - 2. Mounted on ceramic substrate of 1200 mm² x 2.2 mm

Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.



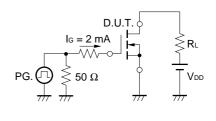
ELECTRICAL CHARACTERISTICS (T_A = 25 °C, All terminals are connected.)

| | CHARACTERISTICS | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|-------------------------------------|----------------------|--|------|------|------|------|
| | Drain to Source On-state Resistance | R _{DS(on)1} | Vgs = 4.5 V, lb = 5.0 A | | 8.6 | 11.0 | mΩ |
| * | | R _{DS(on)2} | Vgs = 4.0 V, Ip = 5.0 A | | 8.8 | 12.0 | mΩ |
| | | R _{DS(on)3} | V _G S = 2.5 V, I _D = 5.0 A | | 11.0 | 15.0 | mΩ |
| | Gate to Source Cut-off Voltage | V _{GS(off)} | V _{DS} = 10 V, I _D = 1 mA | 0.5 | 0.84 | 1.5 | V |
| | Forward Transfer Admittance | yfs | V _{DS} = 10 V, I _D = 5.0 A | 10.0 | 19 | | S |
| | Drain Leakage Current | Ipss | V _{DS} = 20 V, V _{GS} = 0 V | | | 10 | μΑ |
| | Gate to Source Leakage Current | Igss | Vgs = ±12 V, Vps = 0 V | | | ±10 | μΑ |
| | Input Capacitance | Ciss | V _{DS} = 10 V | | 1850 | | pF |
| | Output Capacitance | Coss | V _G S = 0 V | | 610 | | pF |
| | Reverse Transfer Capacitance | Crss | f = 1 MHz | | 320 | | pF |
| | Turn-on Delay Time | td(on) | ID = 5.0 A | | 43 | | ns |
| | Rise Time | tr | V _{GS(on)} = 4.5 V | | 170 | | ns |
| | Turn-off Delay Time | td(off) | V _{DD} = 10 V | | 90 | | ns |
| | Fall Time | tf | R _G = 10 Ω | | 130 | | ns |
| | Total Gate Charge | Q _G | ID = 10 A | | 18 | | nC |
| t | Gate to Source Charge | Qgs | V _{DD} = 16 V | | 3.2 | | nC |
| t | Gate to Drain Charge | Q _{GD} | Vgs = 4.5 V | | 7.8 | | nC |
| | Body Diode Forward Voltage | V _F (S-D) | IF = 10 A, VGS = 0 V | | 0.78 | | V |
| | Reverse Recovery Time | trr | IF = 10 A, VGS = 0 V | | 45 | | ns |
| | Reverse Recovery Charge | Qrr | di/dt = 100 A / μs | | 40 | | nC |

TEST CIRCUIT 1 SWITCHING TIME

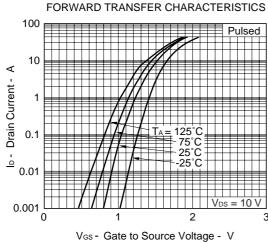
PG. $\bigcap_{RG} RG = 10 \Omega$ $V_{GS} \bigvee_{Wave Form} 0 0 0 0 \%$ $V_{GS} \bigvee_{Wave Form} 0 0 0 0 \%$

TEST CIRCUIT 2 GATE CHARGE

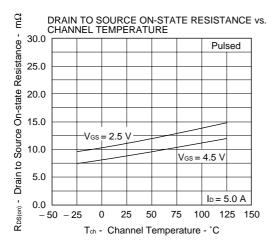


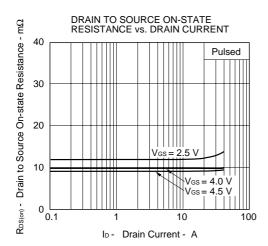


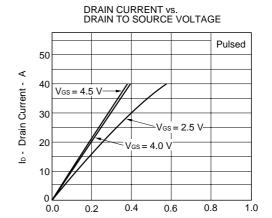
TYPICAL CHARACTERISTICS (TA = 25 °C)

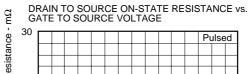




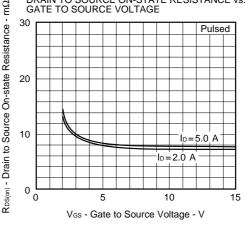


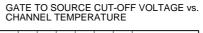


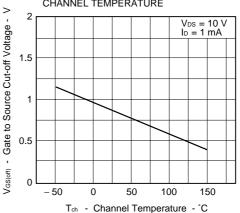




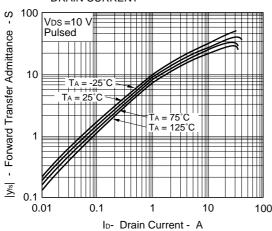
V_{DS} - Drain to Source Voltage - V

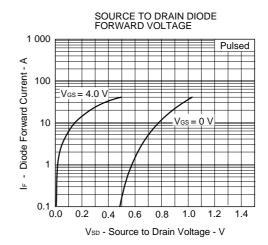


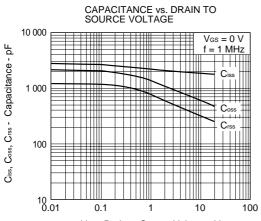


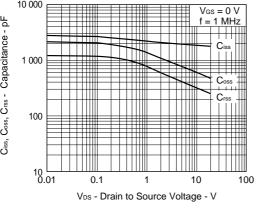


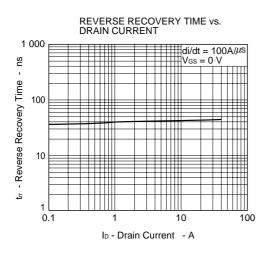
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

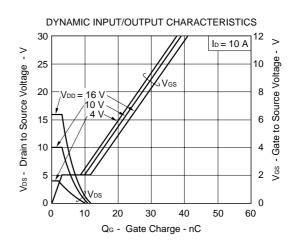


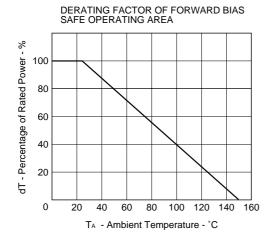


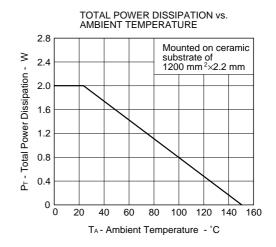


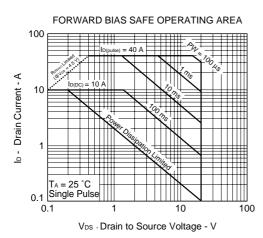




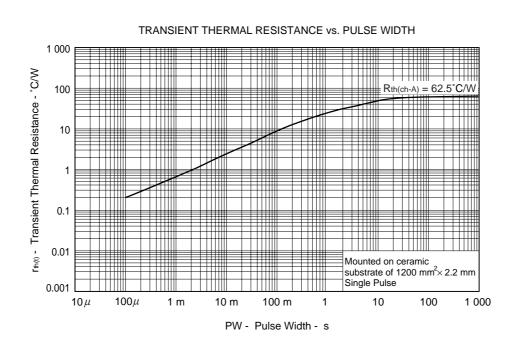








RemarkMounted on ceramic substrate of 1200 mm² x 2.2 mm



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NEC

[MEMO]

NEC μ PA1724

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